

LM613A MD8

DUAL OPERATIONAL AMPLIFIERS, DUAL COMPARATORS, AND ADJUSTABLE REFERENCE

January 2 DIE LAYOUT (C-STEP)						y 29,2007		
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	4					21 19	20 18 17	
	6	DIE ID				15	16 14	
	7	8	9	10 11	12		13	

DIE/WAFER CHARACTERISTICS

Fabrica	ation Attributes	General Die Information		
Physical Die Identification	LM613	Bond Pad Opening Size (min)	100μm x 100μm	
Die Step	С	Bond Pad Metalization	ALUMINUM	
Physi	Physical Attributes		VOM NITRIDE	
Wafer Diameter	150mm	Back Side Metal	Bare Back	
Die Size (Drawn)	2286μm x 2057μm 90.0mils x 81.0mils	Back Side Connection	Floating	
Thickness	406µm Nominal			
Min Pitch	180µm Nominal			

Special Assembly Requirements: Note: Actual die size is rounded to the nearest micron.



DPBU Die Datasheet

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OPERATIONAL /	Die Bond Pad				
(Referenced to	die center, coordi		,	1 '	t Used
SIGNAL	PAD#		RDINATES	PAD	
NAME	NUMBER	X	γ	X	Y
COMP 1 OUT	1	-210	899	100 x	100
COMP 1 IN -	2	-445	899	100 x	100
COMP 1 IN+	3	-1014	899	100 x	100
V+	4	-1014	401	100 x	100
NC	5	-909	226	92 x	92
OP AMP 2 IN -	6	-1014	-266	100 x	100
OP AMP 2 IN +	7	-1014	-899	100 x	100
OP AMP 2 OUT	8	-487	-895	100 x	100
NC	9	-180	-895	100 x	100
FEEDBACK	10	0	-895	100 x	100
CATHODE	11	180	-895	100 x	100
OP AMP 3 OUT	12	487	-895	100 x	100
OP AMP 3 IN -	13	1014	-899	100 x	100
OP AMP 3 IN +	14	1014	-266	100 x	100
NC	15	803	-158	92 x	92
NC	16	1013	-99	92 x	92
V-	17	1014	72	100 x	100
NC	18	1013	267	92 x	92
NC	19	826	323	92 x	92
NC	20	1013	410	92 x	92
NC	21	646	323	92 x	92
COMP 4 IN+	22	1014	899	100 x	100
COMP 4 IN -	23	445	899	100 x	100
COMP 4 OUT	24	210	899	100 x	100



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